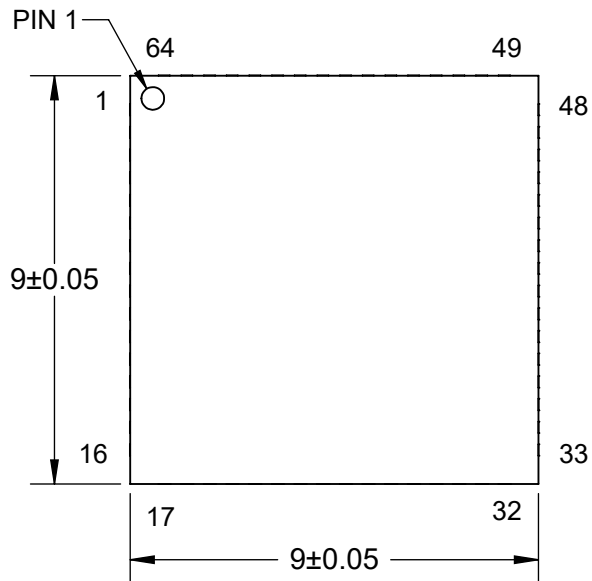
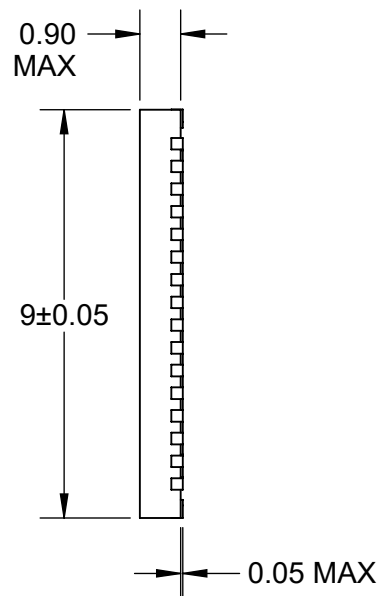


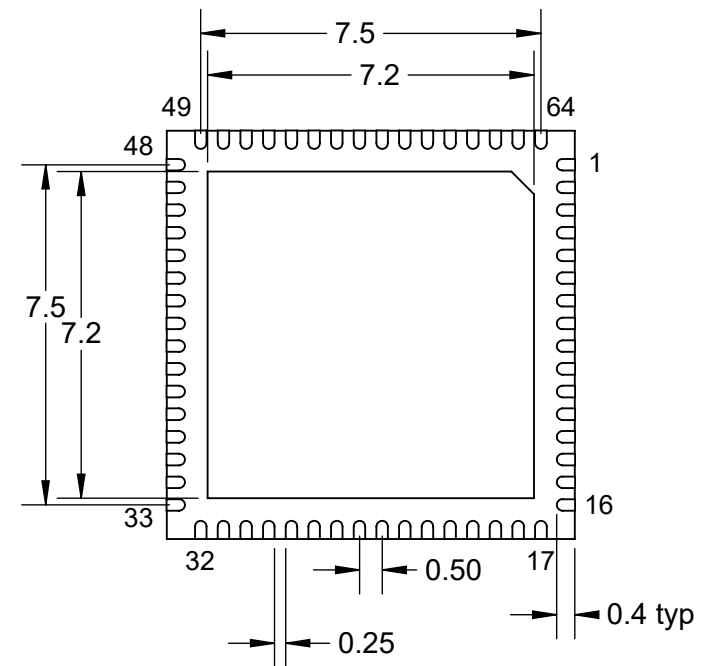
TOP VIEW



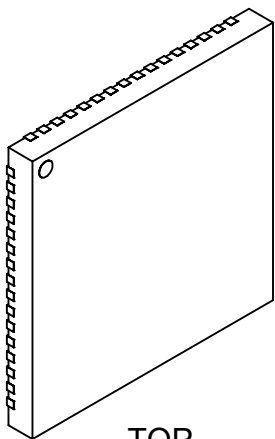
SIDE VIEW



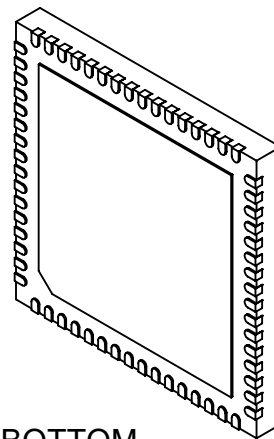
BOTTOM VIEW



MODEL



TOP



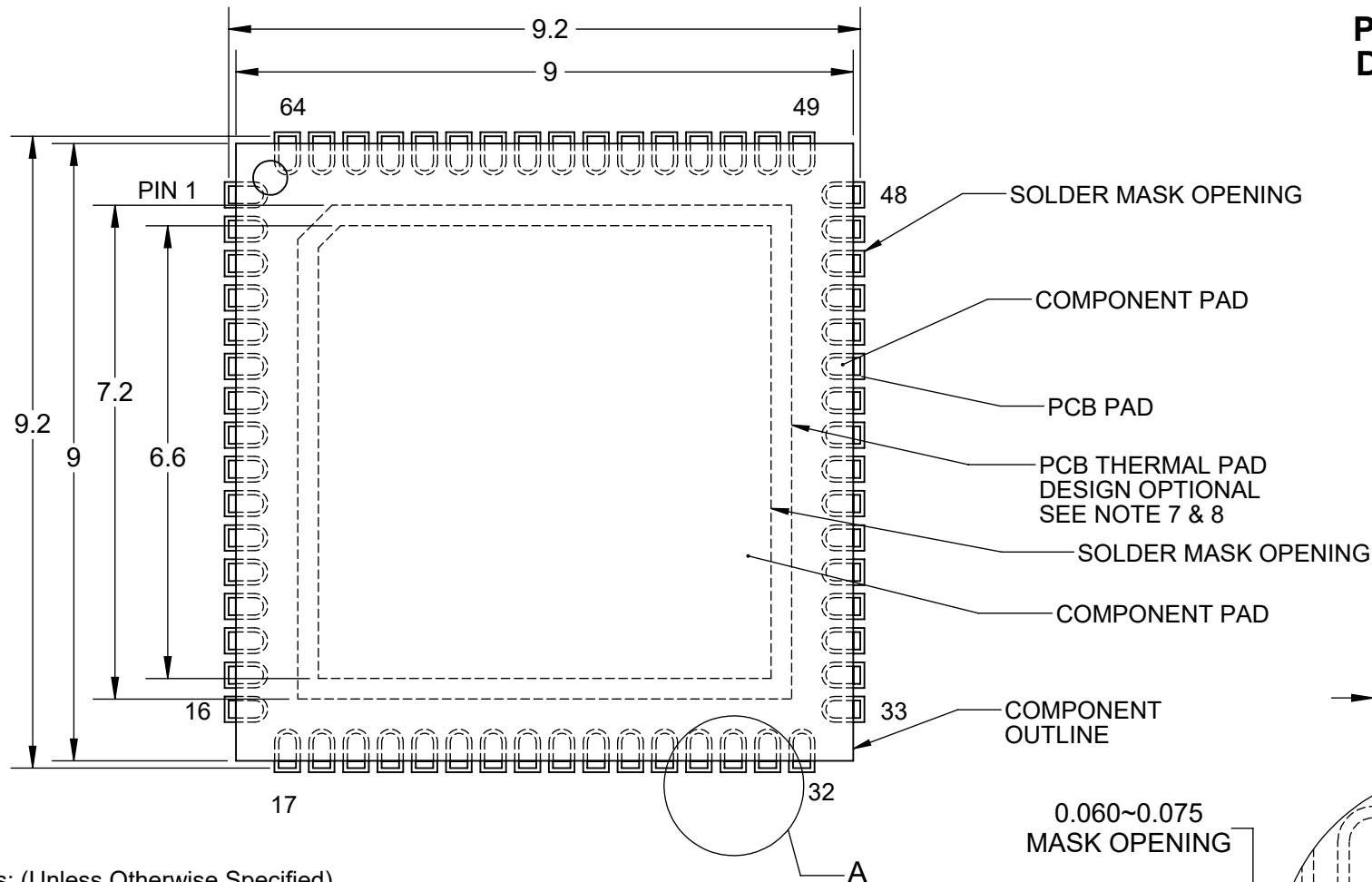
BOTTOM

Notes: (Unless Otherwise Specified).

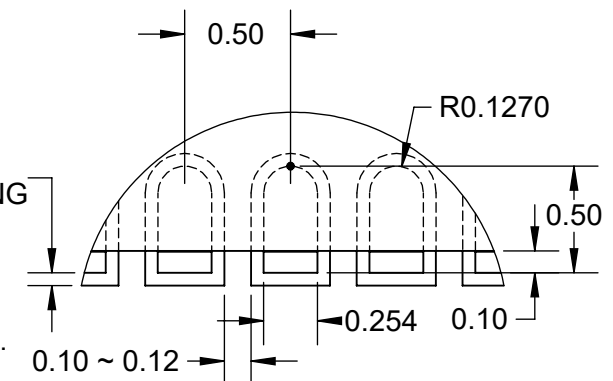
- 1) BODY: PLASTIC, SEMICONDUCTOR GRADE.
- 2) LEAD FRAME: COPPER, C-194 F/H.
- 3) LEAD FRAME PLATING: Sn100 Matte Tin.
- 4) FRAME THICKNESS: 0.203mm.
- 5) DIE PAD: 7.2x7.2mm MAX EXPOSED PAD.
- 6) JEDEC OUTLINE: MO-220.
- 7) DIMENSIONS IN mm.

| | | | | | |
|-------------|-----------|--|------|-------------|--------------|
| APPROVALS | DATE | TopLine® | | | |
| DRAWN T. Au | 7/17/2021 | | | | |
| ENG M. Hart | 7/17/2021 | TITLE QFN 64L 9mm P0.5mm 7.2mm GROUND PAD | | | |
| MFG | | SCALE | SIZE | DRAWING NO. | REV |
| QA | | 6:1 | A | 456413 | A |
| CUST | | DO NOT SCALE DRAWING | | | SHEET 1 OF 3 |
| REVISED | | | | | |

PC BOARD LAYOUT DIMENSIONS IN MM VIEW FROM TOP



0.060~0.075
MASK OPENING



DETAIL A
SCALE 28 : 1

Notes: (Unless Otherwise Specified).

- 1) DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.
- 2) SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (NSMD) SOLDER MASK OPENING (2.4~3.0mils) OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
- 3) ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING. PAD CHAMFER ANGLE MAY VARY.
- 4) PCB LANDS SHOULD BE 0.2mm LONGER THAN THE PACKAGE I/O PADS.
- 5) THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE WIDTH OF THE PACKAGE PADS.
- 6) REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
- 7) THERMAL GROUND PADS MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
 - A) MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
 - B) DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
 - C) PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18 μ m).
 - D) TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THAN THE VIA DIAMETER.
- 8) STENCIL DESIGN MAY BE CHANGED TO SUIT REQUIREMENTS OF THE DESIGNER.
 - A) LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
 - B) THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERTURES INSTEAD OF ONE LARGE APERTURE TO CONTROL PASTE AMOUNTS.
 - C) APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE PAD AREA.

TopLine®

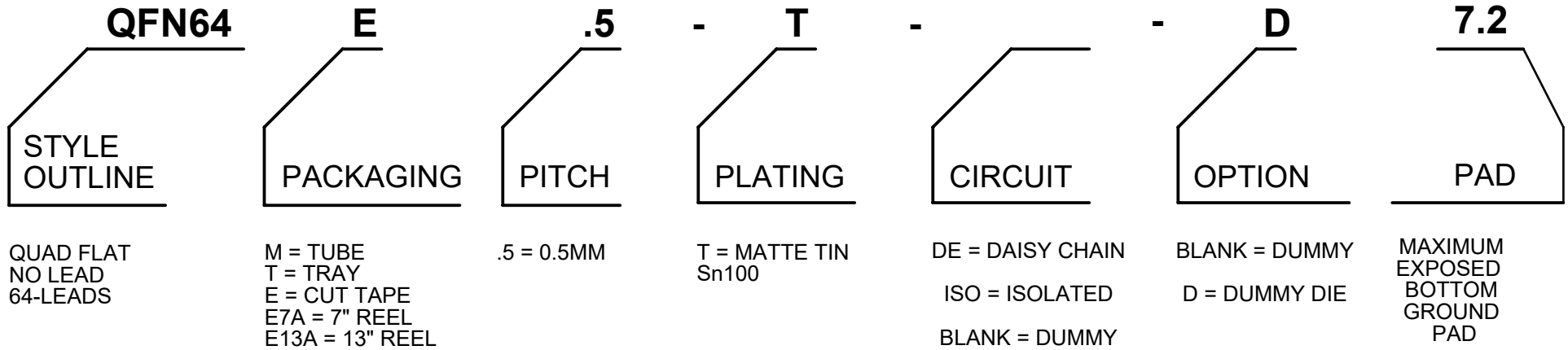
TITLE QFN 64L 9mm P0.5mm
7.2mm GROUND PAD

| SCALE | SIZE | DRAWING NO. | REV |
|-------|------|-------------|-----|
| 8:1 | A | 456413 | A |

DO NOT SCALE DRAWING

SHEET 2 OF 3

PART NUMBERING SYSTEM



| PART NUMBER | DAISY CHAIN | PACKAGING | RoHS Pb-FREE | Plating | DUMMY DIE |
|-------------------|-------------|-------------|--------------|---------|-----------|
| QFN64T.5-T-D7.2 | NO | JEDEC TRAY | YES | Sn100 | YES |
| QFN64E.5-T-D7.2 | NO | CUT TAPE | YES | Sn100 | YES |
| QFN64E7A.5-T-D7.2 | NO | TAPE & REEL | YES | Sn100 | YES |

OTHER PART NUMBER COMBINATIONS AVAILABLE. CONTACT TOPLINE.

| | | | |
|--|-----------|-----------------------|--------------|
| TopLine® | | | |
| TITLE QFN 64L 9mm P0.5mm 7.2mm GROUND PAD | | | |
| SCALE NONE | SIZE A | DRAWING NO. 456413 | REV A |
| DO NOT SCALE DRAWING | | | SHEET 3 OF 3 |